A Survey on Post-Placement Techniques of Multibit Flip-Flops

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Abstract:- Power reduction has become a vital design goal for sophisticated design applications, whether mobile or not. Researchers have shown that multi-bit flip-flop is an effective method for clock power consumption reduction .The underlying idea behind multi-bit flip-flop method is to eliminate total inverter number by sharing the inverters in the flip-flops. The locations of some flip-flops would be changed after this replacement, and thus the wire lengths of nets connecting pins to a flip-flop are also changed. To avoid violating the timing constraints, we restrict that the wire lengths of nets connecting pins to a flip-flops, we transform the coordinate system of cells. In this way, the memory used to record the feasible placement region can also be reduced. Then, we will show how to implement multi-bit flip-flop methodology by XILINX Design Compiler. Experimental results indicate that multi-bit flip-flop is very effective and efficient method in lower-power designs

Keywords:- Power consumption, clock network, multi-bit flip-flops, Post- placement

I. INTRODUCTION

Portable multimedia and communication devices have experienced explosive growth recently. Longer battery life is one of the crucial factors in the widespread success of these products. As such, low-power circuit design for multimedia and wireless communication applications has become very important. In many such products, multi-bit flipflops and delay buffers (line buffers, delay lines) make up a significant portion of their circuits . Reducing the power consumption not only can enhance battery life but also can avoid the overheating problem, which would increase the difficulty of packaging or cooling . Therefore, the consideration of power consumption in complex SOCs has become a big challenge to designers. Moreover, in modern VLSI designs, power consumed by clocking has taken a major part of the whole design especially for those designs using deeply scaled CMOS technologies . Thus, several methodologies have been proposed to reduce the power consumption of clocking. Besides, for a design when considering power consumption, smaller flip-flops are replaced by larger multi-bit flip-flops, device variations in the corresponding circuit can be effectively reduced.

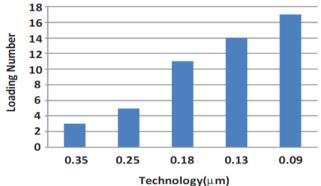


Fig.1 Maximum loading number of a minimum-sized inverter of different technologies

As CMOS technology progresses, the driving capability of an inverter-based clock buffer increases significantly. The driving capability of a clock buffer can be evaluated by the number of minimum-sized inverters that it can drive on a given rising or falling time. Fig. 1 shows the maximum number of minimum-sized inverters that can be driven by a clock buffer in different processes. Because of this phenomenon, several flip-flops can share a common clock buffer to avoid unnecessary power waste. However, the locations of some flip-flops would be changed after this replacement, and thus the wirelengths of nets connecting pins to a flip-flop are also changed. To avoid violating the timing constraints, we restrict that the wire lengths of nets

connecting pins to a flip-flop cannot be longer than specified values after this process. Besides, to guarantee that a new flipflop can be placed within the desired region, we also need to consider the area capacity of the region.

II. MULTI BIT FLIP-FLOP CONCEPT

In this section, we will introduce multi-bit flip-flop conception. Before that, we will review single-bit flip-flop. Figure 2 shows an example of single-bit flip-flop. A single-bit flip-flop has two latches (Master latch and slave latch). The latches need "Clk" and "Clk" signal to perform operations, such as Figure 2 shows.

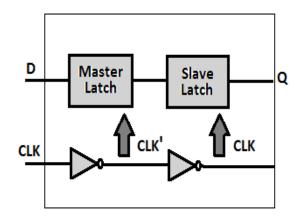


Fig 2: Single-Bit Flip-Flop

In order to have better delay from Clk-> Q, we will regenerate "Clk" from "Clk". Hence we will have two inverters in the clock path. Figure 3 shows an example of merging two 1-bit flip-flops into one 2-bit flip-flop. Each 1- bit flip-flop contains two inverters, master-latch and slave-latch.

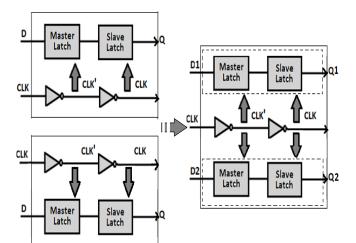


Fig 3: An example of merging two 1-bit flip-flops into one 2-bit flip-flop.

Due to the manufacturing rules, inverters in flip-flops tend to be oversized. As the process technology advances into smaller geometry nodes like 65nm and beyond, the minimum size of clock drivers can drive more than one flip-flop.

Merging single-bit flip-flops into one multi-bit flip-flop can avoid duplicate inverters, and lower the total clock dynamic power consumption. The total area contributing to flip-flops can be reduced as well. By using multi-bit flip-flop to implement ASIC design, users can enjoy the following benefits:

- Lower power consumption by the clock in sequential banked components
- Smaller area and delay, due to shared transistors and optimized transistor-level layout.

III. MULTI BIT FLIP-FLOP METHODOLOGY

In the section, we will introduce that how to use Design Compiler and Faraday's multi-bit flip-flop to implement ASIC design.

A) The criteria of using multi-bit flip-flop

Multi-bit flip-flop cells are capable of decreasing the power consumption because they have shared Inverter inside the flip-flop. Meanwhile, they can minimize clock skew at the same time. To obtain these benefits, the ASIC design must meet the following requirements. The single-bit flip-flops we

want to replace with multi-bit flip-flop must have same clock condition and same set/reset condition.

For post-placement optimization with MBFFs, the previous works separated "MBFF Gen. & Placement" in Fig. 2(c) into two steps: 1) flip-flop merging, and 2) MBFF placement, based on different design objectives. During flipflop merging, both tried to minimize total flipflop power consumption, while proposed to minimize the number of clock sinks (i.e., the total flip-flop number) and net switching power (i.e., the total weighted wirelength). During MBFF placement, proposed to minimize total wirelength, and considered the minimization of net switching power.

In this paper, we address the problem of power optimization with MBFFs at the post-placement stage. We present a new problem formulation for the application of multi-bit flipflops, which simultaneously minimize total flip-flop power consumption and interconnecting wirelength such that both placement density and timing slack constraints are satisfied. Based on the problem formulation, we propose a novel postplacement power optimization flow together with the flip-flop grouping and MBFF placement algorithms to solve the addressed problem. We formulate the flip-flop grouping problem as the *m*-clique finding and maximum-independent-set subproblems. Finally, we introduce the progressive window-based optimization technique to reduce placement deviation and improve runtime efficiency of our algorithms. Experimental results show that our approach is very effective in reducing not only flip-flop power consumption but also clock tree and signal net wirelength when applying multi-bit flip-flops to a design at the post-placement stage.

IV. PROPOSED ALGORITHMS

we propose our algorithms to simultaneously reduce total flipflop power consumption and interconnecting wirelength at the post-placement stage. First of all, the MBFF consumption of an MBFF cell divided by its bit number, PfmOnce the MBFF cells in the cell library are sorted, the most power-efficient MBFF cell is then iteratively extracted. Our algorithms always replace a group of flip-flops with the most power-efficient MBFF cell during the optimization. After an *m*-bit flip-flop cell is extracted, two major steps, including flip-flop grouping and MBFF creation and placement, in the flow will be performed based on the technique of progressive window based optimization. The first step finds a set of *m*-bit flip-flop groups in the design while the second step determines the position of each *m*-bit flip-flop group and verifies the legality of the position. A legal position of an *m* bit flip-flop group means that placing an *m*-bit flip-flop group is legal, an *m*-bit flip-flop cell is then created to merge all the flipflops in the *m*-bit flip-flop group. Otherwise, the flip-flops in the *m*-bit flip-flop group cannot be merged.

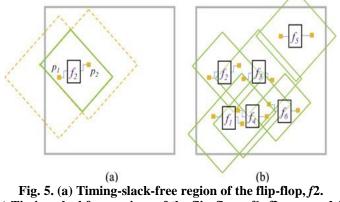
A. Grouping of Flip-Flops

When grouping a set of flip-flips, the timing slacking constraints between any flip-flop and all its connected pins should be first considered. According to the timing slacking constraints, we explore all possible combinations of flip-flop groups for flip-flop merging. Finally, we try to select maximal cells in the cell library are sorted in ascending order with respect to the flip-flop power consumption per bit non-conflicted flip-flop groups from all the combinations.

1) Consideration of Timing Slack Constraints:

Based on every flip-flop should be placed in the timing-slack-free region which is defined as follows. Definition 1: A timing-slack-free region (TSFR) of a flipflop is a region where the flip-flop is placed within the maximum allowable distance from its connected pins such that the timing slack constraints are satisfied.

Fig. 5(a) illustrates the TSFR of f^2 which is a tilted rectangular region intersected by the Manhattan rings of p^1 and p^2 . Every point on the Manhattan ring of p^1 (p^2) has the same Manhattan distance from p^1 (p^2), which is equal



(b) Timing-slackfree regions of the flip-flops, *f*1, *f*2, ..., and *f*6.

to $d\max(p1, f2)$ ($d\max(p2, f2)$). Fig. 5(b) further shows all the TSFRs of $f1, f2, \ldots$, and f6 in the same design. According to the definition of the TSFR, a set of flip-flops can be grouped and replaced by an MBFF if there exists an intersection region of the TSFRs of all the flip-flops. In Fig. 5(b), f2 and f5 cannot be grouped and merged by an MBFF since the TSFRs of f2 and f5 are independent without any intersection. On the contrary, f1 and f2 can be grouped and merged by an MBFF because the merged MBFF can be placed in the intersection of the TSFRs of f1 and f2 such that the timing slack constraint of the merged MBFF is met. Such flip-flop group of f1 and f2 is called a timing-slack-free group which is defined in the following.

Definition 2: A timing-slack-free group (TSFG) is a flipflop group in which all the flip-flops can be merged by an MBFF such that the timing slack constraints between the MBFF and all its connected pin are satisfied.

2) Exploration of m-Bit Flip-Flop Groups:

Before exploring the *m*-bit TSFGs in a design, we construct the TSFR intersection graph which is defined in Definition 3. Fig. 6(a) shows The TSFR intersection graph representing the relationship of the TSFRs in Fig. 5(b). The vertices, $v1, v2, \ldots, v6$, represent the six flip-flops, $f1, f2, \ldots, f6$, respectively. If there is an intersection between the TSFRs of two flip-flops, there is an edge between the corresponding vertices. G(V, E), where each vertex, vi, corresponds to a flip-flop, fi, in the design, and an edge, eij, between vi and vj exists if there is an intersection between the TSFRs of fi and fj. Once the TSFR intersection graph of a design is constructed, we can explore all the *m*-bit TSFGs in the design by finding all the *m*-cliques in the TSFR intersection graph. Each *m*-clique in The graph corresponds to an *m*-bit TSFG. The problem of finding all *m*-cliques in the graph can be well solved by applying the branch-and-bound and backtracking algorithms using a search tree as shown in Fig. 6. From the example, we can find all 4-cliques, including $\{n1, n2, n3, n4\}$ and $\{n1, n3, n4, n6\}$, in the graph. Consequently, the set of 4-bit TSFGs, G4, of the design in Fig. 5(b) contains two TSFGs, $\{g41, g42\}$, where g4

$$g1 = \{f1, f2, f3, f4\}$$
 and $g4$
 $g2 = \{f1, f3, f4, f6\}.$

3) Selection of Flip-Flop Groups:

After exploring these of *m*-bit TSFGs of a design denoted by $Gm = \{gm1, gm2, \ldots, gmk\}$, the next problem is how to select the maximum number of non-conflict *m*-bit TSFGs for more

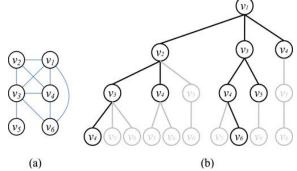


Fig. 6. (a) TSFR intersection graph representing the relationship among the TSFRs in Fig. 5(b). (b) Branch-and-bound and backtracking algorithms which find all 4-vertex cliques in (a).

Power saving and wirelength reduction. The selection of nonconflict TSFGs can be formulated by finding the maximum independent set (MIS) in Gm. In the previous example, the MIS in G4 is either $\{g41\}$ or $\{g42\}$ since f1, f3, and f4 belong to both g41 and g42. The independent set of TSFGs is defined as follows.

B. Placement of Flip-Flop Groups

Once the IS of TSFGs is obtained, a proper location for the MBFF corresponding to a TSFG should be searched.

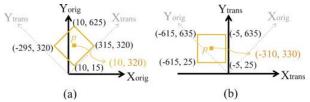


Fig. 7. (a) Original coordinate system. (b) Transformed coordinate system.

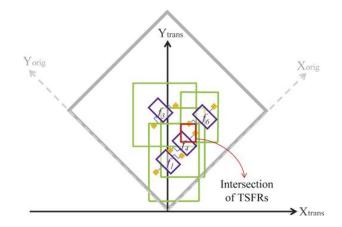


Fig. 8. Example of converting the design in

Fig. 5(b) from the original coordinate system into the transformed coordinate system. The intersection denotes the valid placement region of the TSFG, $g42 = \{f1, f3, f4, f6\}$.

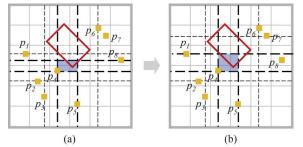


Fig. 9. Placement area of an MBFF with the consideration of interconnecting wire length.
(a) Placement area bounded by the median coordinates of the eight pins.
(b) Enlarged placement area when placing an MBFF in the area in (a) is not feasible.

This sub section, the transformation of the coordinate system is first introduced to improve the computational efficiency when calculating the intersection of several TSFRs. The placement bins and grids are then searched for each MBFF corresponding to a TSFG according to the intersection of TSFRs. When finding a placement bin or a placement grid for each MBFF, we try to minimize the interconnecting wirelength while satisfying the placement density constraint.

1) Transformation of Coordinate System:

According to Definitions 1 and 2, the MBFF corresponding to a TSFG should be placed within the intersection of the TSFRs of all the flip-flops in the TSFG. Since all the TSFRs are tilted in 45° with respect to the placement coordinate system, the intersection of the TSFRs is also tilted in 45°. To efficiently calculated the coordinates of the intersection from the coordinates of the TSFRs, we transform the coordinate system based on the transfer functions defined in (4). The difference between the original and the transformed coordinate systems

is demonstrated in Fig. 7. Both coordinate systems can be transformed back and forth based on the transfer and inverse transfer functions in

Fig. 8 further shows an example of converting the design in Fig. 5(b) into the transformed coordinate system. After the transformation, all the tilted rectangular regions of the TSFRs become non-tilted. Consequently, it becomes much

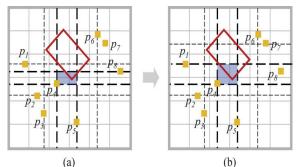


Fig. 10. Placement area of an MBFF with the consideration of interconnecting wirelength.
(a) Placement area bounded by the median coordinates of the eight pins. (b) Enlarged placement area when placing an MBFF in the area in (a) is not feasible

Easier to calculate the coordinates of the intersection of the TSFRs of all flip-flops in the TSFG, $g42 = \{f1, f3, f4, f6\}$. Once the coordinates of the intersection region in Fig. 8 are calculated in the transformed coordinate system, they should be transformed back to the original coordinate system such that the coordinates of the tilted rectangular placement region in the original coordinate system can be obtained.

2) Consideration of Placement Density:

To find a legal placement for an MBFF corresponding to a TSFG within the tilted rectangular placement region, or the TSFR of the MBFF, only the placement bins covered by the tilted rectangular placement region should be considered. To collect all the placement bins, the bins intersected by each boundary of the tilted rectangular placement region should be first identified as shown in Fig. 9(a) and (b). The bins surrounded by these intersected bins can be found and collected accordingly. To better consider the placement density during MBFF placement, the bin with the lowest placement density is chosen to accommodate the MBFF corresponding to a TSFG. If there is no valid placement grid within the bin, the bin with the second lowest placement density is then chosen. The grid searching process is repeated until a valid placement grid for the MBFF is found.

3) Consideration of Interconnecting Wire length:

In addition to considering the placement densities of the bins within the TSFR of an MBFF corresponding to a TSFG, it is also required to minimize the interconnecting wirelength when placing the MBFF. To find a position for the MBFF with shorter wirelength, the area bounded by the median coordinates of all pins connected to the MBFF is first considered as shown in Fig. 10(a). In this example, the median coordinates of the eight pins are xp4, xp5, yp4, and yp8 in both axes. Once the area bounded by the median coordinates of all pins is obtained, a grid-searching process is performed to find a valid placement grid. During the grid-searching process, the bin with the lowest placement density, which contains grids inside the TSFR and the bounded area of the median coordinates of all pins, is first chosen. For example, in Fig. 11(a), the bin, b22, is

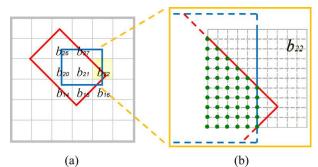


Fig. 11. Example of finding valid placement grids during grid-searching process. (a) Bins containing placement grids inside both the TSFR of the MBFF and the area bounded by the median coordinates of all pins connected to the MBFF. (b) All possible placement grids in the bin, *b*22.

The one with the lowest placement density. A valid placement grid is then searched among all possible placement grids in b22 as shown in Fig. 11(b).

If there is no valid placement grid in the bin intersected by both the area bounded by the coordinates of the pins and the TSFR, or the tilted rectangular placement region, the area bounded by the coordinates of the pins is enlarged to the next pitch which is the closest one from the current pitches. In Fig. 10(b), yp1 is the closest pitch from yp8 compared with all the other neighboring pitches. The enlarged area for wirelength minimization is then surrounded by xp4, xp5, yp4, and yp1. The process is continued until a valid placement grid for the MBFF is found.

V. CONCLUSION

In this paper, we presented a new problem formulation of post-placement optimization with MBFFs to optimize the power consumption of the clock network. Based on the problem formulation, we proposed flip-flop grouping and MBFF placement algorithms to simultaneously minimize flip-flop power consumption and interconnecting wirelength such that both placement density and timing slack constraints are satisfied. Using Multi-Bit Flip-flop in combination with gated tree drive is an effective and efficient implementation methodology to reduce the power consumption by merging single-bit flip-flop. In this paper, we have implemented design with XILINX Design Compiler and Faraday's multi-bit flip-flop.

Experimental results indicate that multi-bit flip-flop is very effective and efficient method in lowerpower designs. We will use this methodology to implement real ASIC project in the future

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